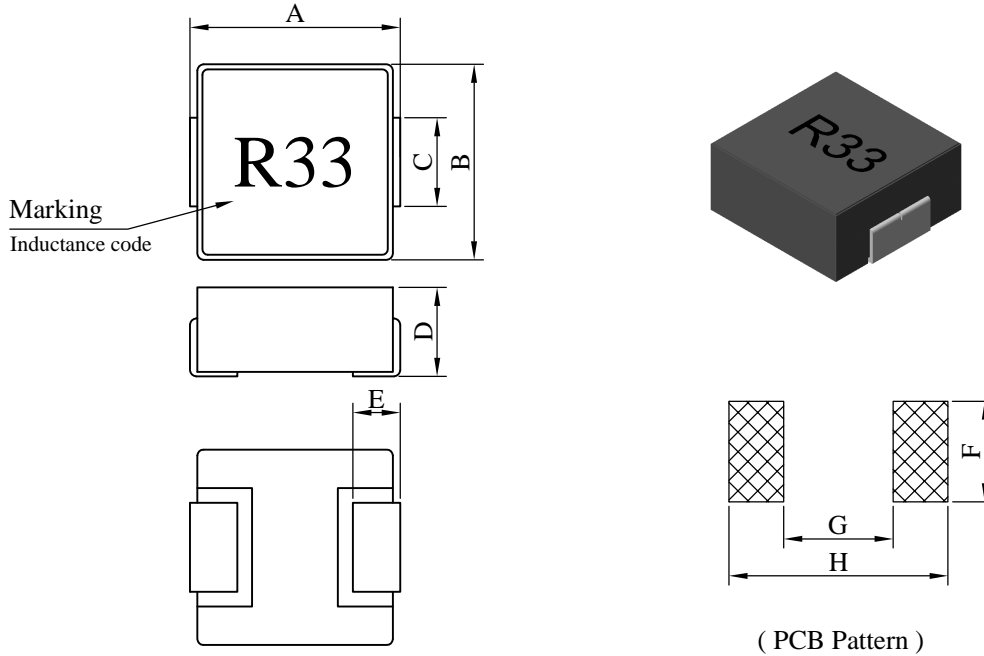


# SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.		HE0630□□□□L□-□□□	
		REV.	20200519-E	PAGE	1

## I . Configuration and dimensions :



Unit : mm

A	B	C	D	E	F	G	H
7.10 ±0.30	6.60 ±0.30	3.00 ±0.30	3.00 max.	1.60 ±0.50	3.40 ref.	3.70 ref.	7.40 ref.

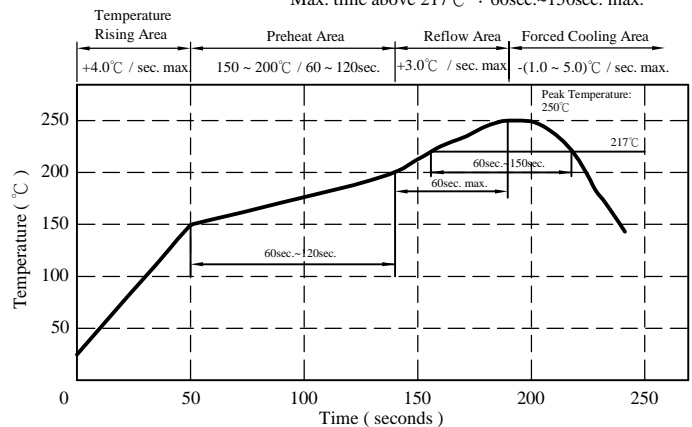
## II . Description :

- a . Powder molding construction
- b . Magetically shielded
- c . Enamelled copper wire : N class
- d . Product weight : 0.75g ( ref. )
- e . Moisture sensitivity Level 2a
- f . Products comply with RoHS' requirements
- g . Halogen free

Peak temp. : 250°C max.  
 Max. peak temp. - 5°C : 30sec. max.  
 Max. time above 217°C : 60sec.~150sec. max.

## III . General specification :

- a . Storage temp. : -55°C ~ +125°C
- b . Operating temp. : -55°C ~ +125°C  
( Temp. rise included )
- c . Resistance to solder heat : 260°C. 10 sec.



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# SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.	HE0630□□□□L□-□□□		
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IV . Electrical characteristics :

DWG. No.	Inductance ( μH )	RDC ( mΩ )		Isat ( A ) typ.	Irms ( A ) typ.
		typ.	max.		
HE0630R33ML□-□□□	0.33 ±20%	3.0	3.5	25.0	21.0
HE0630R36ML□-□□□	0.36 ±20%	3.3	3.9	24.0	20.0
HE0630R47ML□-□□□	0.47 ±20%	3.5	4.1	20.0	18.0
HE0630R56ML□-□□□	0.56 ±20%	3.9	4.5	18.0	16.5
HE0630R68ML□-□□□	0.68 ±20%	4.8	5.3	17.0	16.0
HE0630R82ML□-□□□	0.82 ±20%	5.4	6.0	16.0	14.0
HE06301R0ML□-□□□	1.00 ±20%	6.7	7.4	15.0	12.0
HE06301R2ML□-□□□	1.20 ±20%	7.8	10.0	14.0	10.0
HE06301R5ML□-□□□	1.50 ±20%	10.6	12.1	14.0	10.0
HE06302R2ML□-□□□	2.20 ±20%	13.5	15.0	10.0	8.0
HE06302R5ML□-□□□	2.50 ±20%	16.0	18.0	10.0	7.0
HE06303R3ML□-□□□	3.30 ±20%	18.0	22.0	9.5	6.5
HE06304R7ML□-□□□	4.70 ±20%	28.0	33.0	6.5	5.5
HE06305R6ML□-□□□	5.60 ±20%	39.0	42.0	6.0	5.5
HE06306R8ML□-□□□	6.80 ±20%	43.0	50.0	6.0	4.5
HE06308R2ML□-□□□	8.20 ±20%	54.0	60.0	6.0	4.5
HE0630100ML□-□□□	10.00 ±20%	62.0	68.0	5.5	4.0
HE0630150ML□-□□□	15.00 ±20%	110.0	125.0	3.0	3.5
HE0630220ML□-□□□	22.00 ±20%	180.0	200.0	3.0	2.3

- 1). Electrical specifications at 25°C
- 2). Inductance Test Condition. :500kHz / 0.25V
- 3). Isat base on ΔL / L0A=30% typ.(Approximately transient current)
- 4). Irms base on Temp. rise 40°C typ.
- 5). Rated Voltage : 50V max.

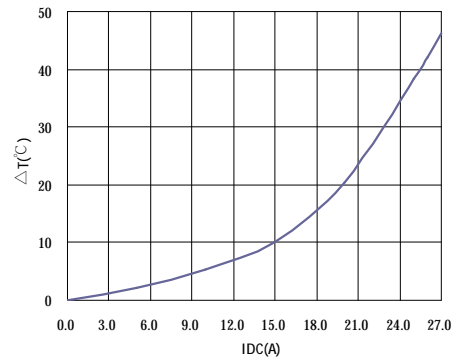
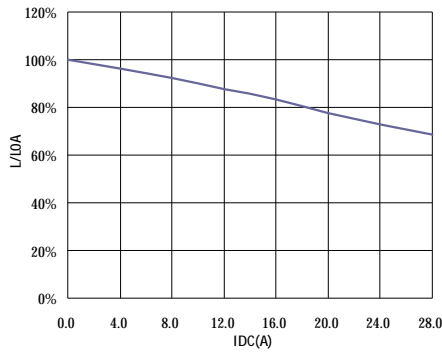
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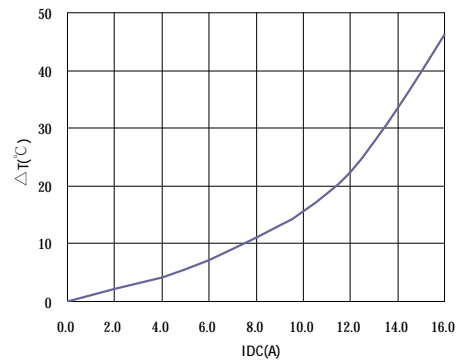
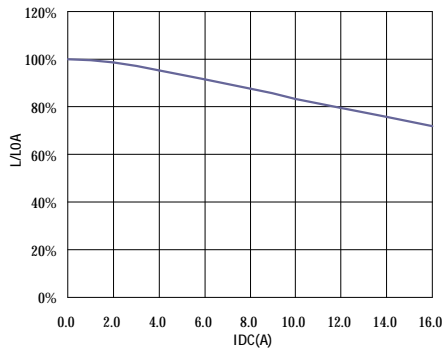
PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.	HE0630□□□□L□-□□□		
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V . Curve :

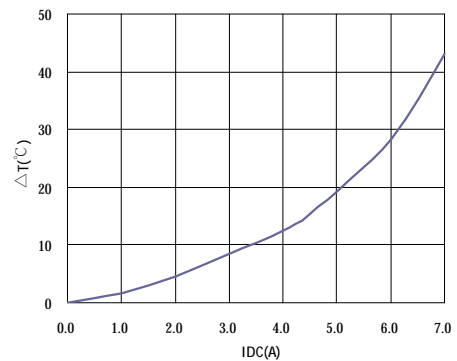
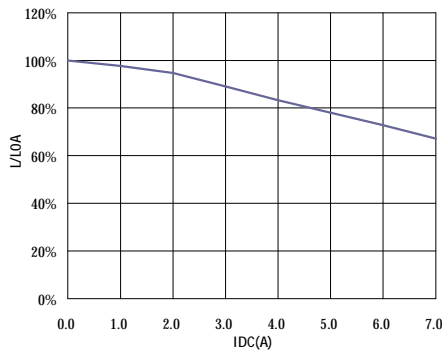
HE0630R36ML□



HE06301R2ML□



HE06308R2ML□



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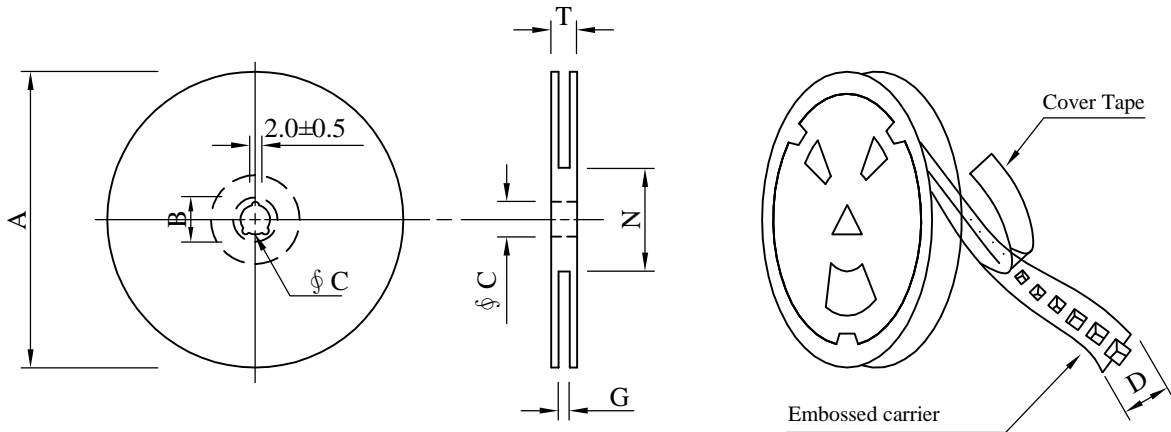
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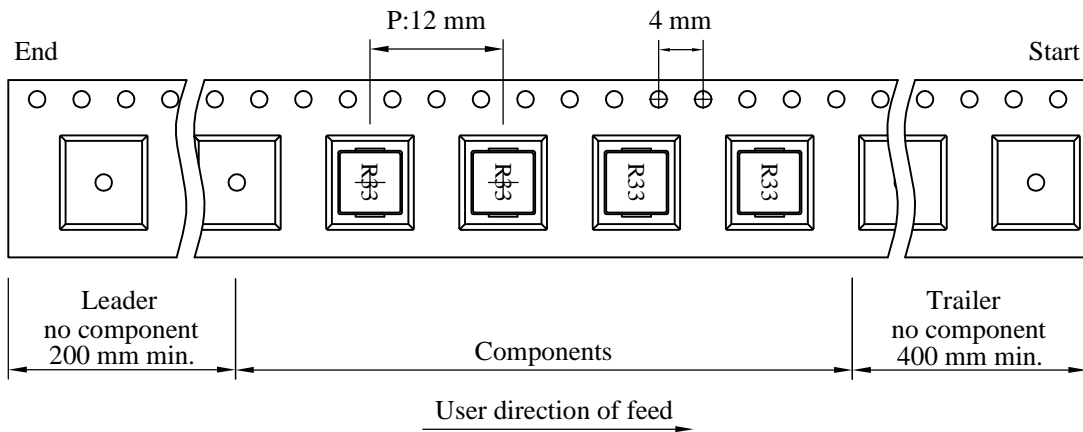
PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.		HE0630□□□□L□-□□□	
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## VI . Packaging information :

### (1) Configuration



※Carrier tape width : D



### (2) Dimensions

Unit:mm

Style	A	B	C	D	G	N	T
13 - 16	330	21±0.8	13±0.5	16	18 <sup>+0</sup>	50 <sup>-0</sup>	22.4

### (3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	1,000	1,100	13 - 16	4,000	6.00	38 x 37 x 22

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# SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.	HE0630□□□□L□-□□□		
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## VIII . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature : 85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperance. 2.No marking blurred. 3.Inductance shall not change more than ±20%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitud : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature : 250±5℃. 2.Time ( temp. ≥ 217℃ ) : 60~150 Seconds. 3.IR reflow times : 3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 seconds. 2.Saturation current	Inductance shall not drop more than 30% typ.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ typ.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing : 150±5℃ / 16Hours±30 min. 2.Peak temperature : 240±5℃ 3.Time ( temp. ≥ 217℃ ) : 60~150 seconds. 4.IR reflow times : 1 time.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature : -55℃~125℃ 2.Room temperature : 25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time : 6 times (Every side of sample drop 2 times)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.

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